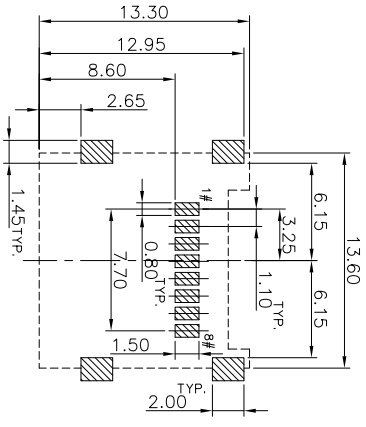
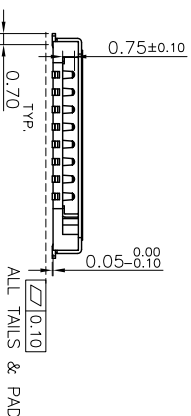
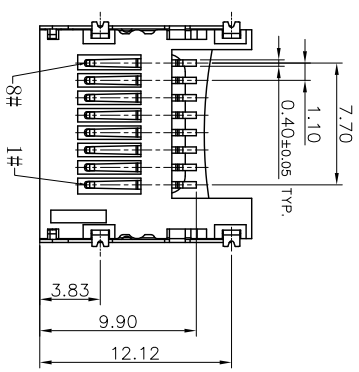


SHELL LOCK

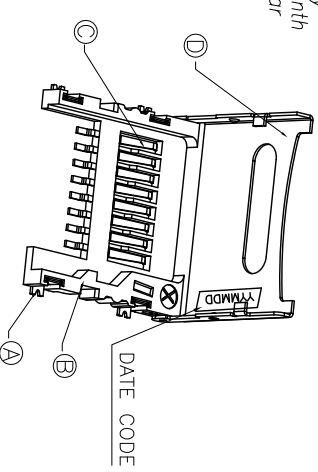


RECOMMENDED PCB PATTERN LAYOUT
TOLERANCE: ±0.05



REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A	PDR NO:1T00201-2A		Tom	2010.05.11
B	ECN NO:S100813		ANDY	2010.10.25

- SPECIFICATIONS:
- MATERIAL : HOUSING:HIGH TEMPERATURE THERMOPLASTIC. UL94V-0-BLACK
SHELL:STAINLESS STEEL.
CONTACT:COPPER ALLOY.
SOLDER PAD: COPPER ALLOY.
 - PLATING:
CONTACT: GOLD FLASH PLATED OVER,
50u" Min. Ni.
50u" Min. Ni.
SOLDER PAD:100u" Min. Sn PLATING OVER
50u" Min. Ni.
 - ELECTRICAL CHARACTERISTIC:
CONNECT RESISTANCE:80 MILLIOHMS/PRE PIN Max.
INSULATION RESISTANCE:1000 MEGAOHMS Min.
VOLTAGE WITHSTAND:500V AC for 1 minute
 - TO CONFORM TO SINGATRON HARADOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATI MARK ON JACK: ©
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING: Ⓢ
 - DATE CODE: YMMDD



Pin No	Name	Type	DESCRIPTION
1	DAT2	I/O/PP	Data Line [bit2]
2	CD/DAT3	I/O/PP	Card Detect Data Line [bit3]
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Clock
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Data Line [bit0]
8	DAT1	I/O/PP	Data Line [bit1]

	A	B	C	D	E
DESCRIPTION	Solder Pad	Housing	Contact	Shell	MYLAR
QTY	4	1	8	1	1
MATERIAL	COPPER ALLOY.	HIGH TEMPERATURE THERMOPLASTIC. UL94V-0.	COPPER ALLOY.	STAINLESS STEEL.	MYLAR 0.06t
PLATING & COLOR		BLACK	Gold Flash	清洗	

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

T-FLASH CARD CONNECTOR

ANDY PART NO. 2CA2000-002111

LUSSSEN SCALE 1:1 UNIT: mm

TONY SIZE: A3 SHEET: 10F1 REV: B

CUSTOMER COPY